# ● PRINTER RUSH ●
## (PTO ASSISTANCE)

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| **Application :** | 10/666711 | **Examiner :** | Oakley Jr. | **GAU :** | 2877 |
| **From:** | PAP | **Location:** | (IDC) FMF FDC | **Date:** | 3/28/05 |

Tracking #: 06034562 Week Date: 11/1/04

| DOC CODE | DOC DATE | MISCELLANEOUS |
|---|---|---|
| ☐ 1449 | | ☐ Continuing Data |
| ☐ IDS | | ☐ Foreign Priority |
| ☐ CLM | | ☐ Document Legibility |
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| ☐ SRFW | | ☐ Other |
| ☐ DRW | | |
| ☐ OATH | | |
| ☐ 312 | | |
| ☑ SPEC | 9/18/2003 | |

[RUSH] **MESSAGE:** Please supply missing data on Page 14, line 28 of Specification.

thank you.

[XRUSH] **RESPONSE:** Corrected

Tarek Fahmi 405-720-8598 **INITIALS:** PS

NOTE: This form will be included as part of the official USPTO record, with the Response document coded as XRUSH.

REV 10/04

63170190

Email Examiner

10/666,761

filtering that is known in the art. For example, U.S. Patent 5,177,559, to Batchelder et al., whose disclosure is incorporated herein by reference, describes a dark-field imaging system for inspecting repetitively-patterned integrated circuits, using an opaque spatial filter to attenuate spatial frequency components corresponding to the wafer pattern. U.S. Patent 5,276,498, to Galbraith et al., whose disclosure is also incorporated herein by reference, describes a system for performing dark-field surface inspection using a scanned, focused laser beam and an adaptive spatial filter consisting of a liquid crystal light valve array.

As another example, U.S. patent application 09/595,902, to Milshtein et al., which is assigned to the assignee of the present patent application and whose disclosure is incorporated herein by reference, describes a spatial filtering system using a set of masks produced in chrome on a transparent substrate and positioned using a combination of filter wheel and fine translation motors. This patent application also describes a method for *a priori* determination of the optimal filter configuration by analyzing a high-resolution two-dimensional image of the wafer plane, in combination with the known properties of the materials and three-dimensional configuration of the substrate. Reflective spatial filters may also be used, as described in another U.S. patent application 10/050,890 entitled "Patterned Wafer Inspection Using Spatial Filtering," filed 1/15/02, which is likewise assigned to the assignee of the present patent application and whose disclosure is incorporated herein by reference. This application also describes a method that can be used to determine the spatial

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